

OL-IP4340CX15

wafer-level chip-size package; 15 bumps; (4 x 4 -C2); 0.4 mm pitch; 1.56 mm x 1.56 mm x 0.47 mm body

8 June 2017

Package information

1. Package summary

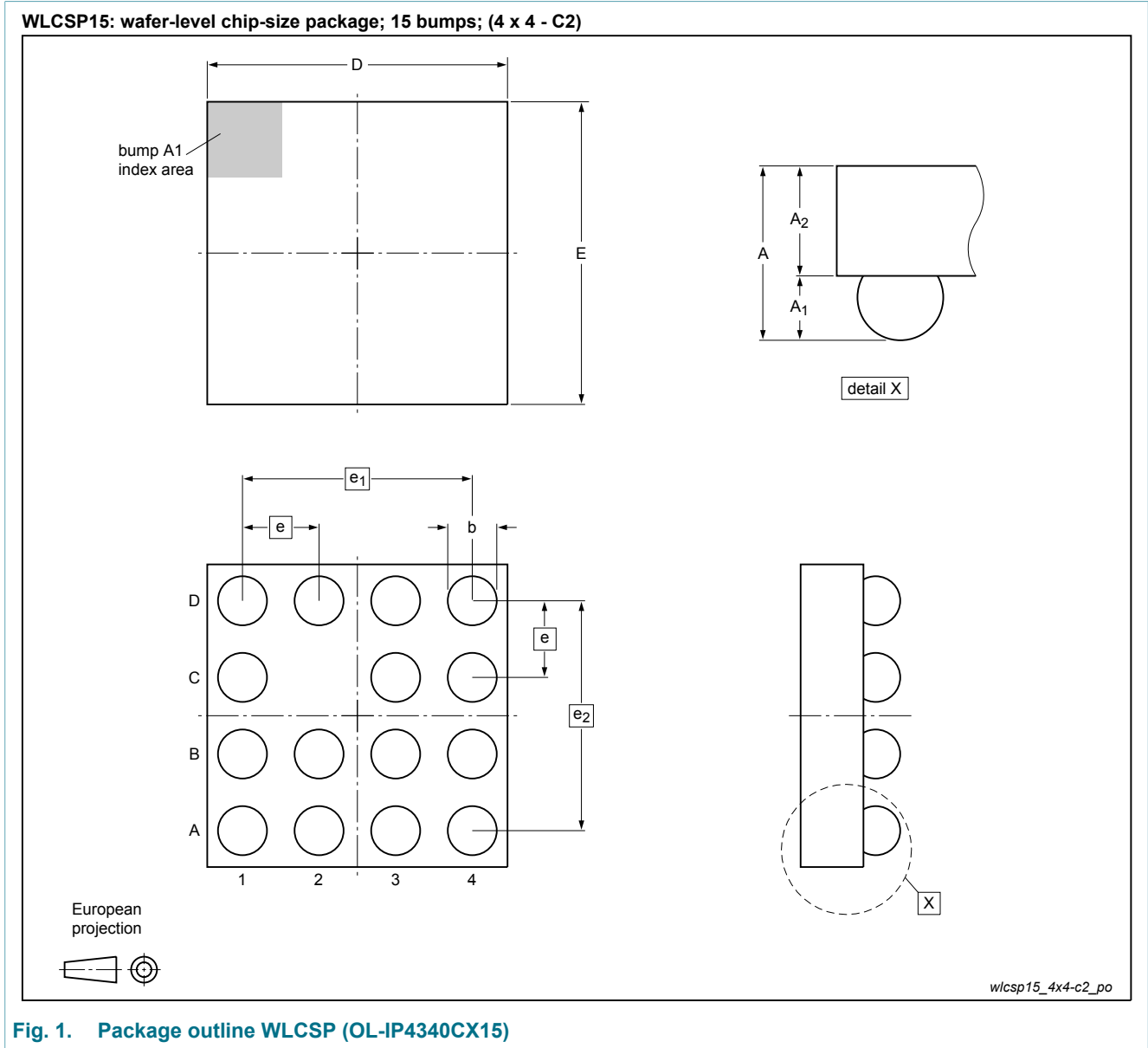
Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	25-5-2007
Manufacturer package code	WLCSP15

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.51	-	1.56	1.61	mm
E	package width	1.51	-	1.56	1.61	mm
A	seated height	0.44	-	0.47	0.5	mm
A ₂	package height	0.26	-	0.27	0.28	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	15	-	

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2. Package outline



3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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Date of release: 8 June 2017
